

ALTERNATION HISTORY RECORDS 变更记录

Date 日期	Version 版本	Mark 标记	Page 页码	Description 描述	Drafter 制定者	Approver 审批者
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1. INTRODUCTION

This Series green type capacitors are manufactured by using green materials without lead and cadmium. These capacitors feature series connection of multi-layer capacitor units in a MLCC to realize high voltage performance. Reliable performances are built-in through exact formulation of dielectric powders, preparation of conductive paste, advanced automatic manufacturing, and strict quality control to assure excellent control in dielectric thickness, electrode integrity, and electrode-to-termination continuity.

2. FEATURES

- a. Special interior design offers high voltage rating in a given case size.
- b. High reliability and stability.
- c. RoHS compliant

3. APPLICATIONS

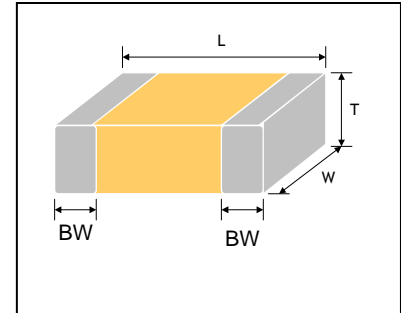
- a. DC to DC converter.
- b. High voltage coupling/DC blocking.
- c. Back-lighting inverters.
- d. LAN/WLAN interface.
- e. Modem.
- f. Power supplies.

4.HOW TO ORDER

1808	B	102	K	302	K	A	-G
<u>Size</u>	<u>Dielectric</u>	<u>Capacitance</u>	<u>Tolerance</u>	<u>Rated voltage</u>	<u>Termination</u>	<u>Packaging</u>	<u>Suffix</u>
Inch(mm) 0805(2012) 1206(3216) 1210(3225) 1808(4520) 1812(4532)	N:NPO B:X7R	Two significant digits followed by no. of zeros. And R is in place of decimal point. eg.: R47=0.47pF 0R5=0.5pF 1R0=1.0pF 100=10x10 ⁰ =10pF	B =±0.1pF C =±0.25pF D =±0.5pF F = ± 1% G =±2% J =±5% K =±10% M =±20%	Two significant digits followed by no. of zeros. And R is in place of decimal point. 102 = 1000 VDC 202 = 2000 VDC 302 = 3000 VDC	N : 0.50 ± 0.05mm A : 0.60 ± 0.10mm B : 0.85 ± 0.15mm C : 0.95±0.10mm D : 1.25 ± 0.20mm G : 1.60 ± 0.20mm P : 1.60+0.30/-0.10mm K : 2.00 ± 0.20mm M : 2.50 ± 0.30mm U : 2.80 ± 0.30mm	K=0.5kpcs/ reel A=1kpcs/ reel B=2kpcs/ ree C=3kpcs/ reel D=4kpcs/ reel I=10kpcs/ reel	

5. EXTERNAL DIMENSIONS

Size Inch (mm)	L (mm)	W (mm)	T(mm)	BW min (mm)
0805(2012)	2.00 ± 0.15	1.25 ± 0.1	1.35 max.	0.50
1206 (3216)	3.20±0.20	1.60±0.20	1.80 max.	0.30
1210 (3225)	3.20±0.40	2.50±0.30	2.80 max.	0.30
1808 (4520)	4.50±0.40	2.00±0.20	2.20 max.	0.26
1812 (4532)	4.50±0.40	3.20±0.30	2.80 max.	0.26



6. GENERAL ELECTRICAL DATA

Dielectric	NPO		X7R	
	Size	0805, 1206, 1210, 1808, 1812		0805, 1206, 1210, 1812, 1808, 1825, 2220, 2225
Rated voltage (WVDC)	1KV, 2KV, 3KV		1KV, 2KV, 3KV	
Capacitance range*	1KV	1.5pF ~ 2.2nF	1KV	100pF ~ 100nF
	2KV	1.5pF ~ 1.2nF	2KV	150pF ~ 12nF
	3KV	2.2pF ~ 470pF	3KV	150pF ~ 3.9nF
Capacitance tolerance	Cap≤5pF: B (±0.1pF), C (±0.25pF) 5pF<Cap<10pF: C (±0.25pF), D (±0.5pF) Cap≥10pF: F (±1%), G (±2%), J (±5%),K (±10%)		J (±5%), K (±10%), M (±20%)	
Tan δ*	Cap<30pF: Q≥400+20C Cap≥30pF: Q≥1000		≤2.5%	
Insulation resistance at 500Vdc for 60 seconds	≥100GΩ or R·C≥1000 whichever is smaller		≥10GΩ or R·C≥500Ω·F whichever is smaller	
Operating temperature	-55 to +125°C			
Temperature coefficient	±30ppm / °C		±15%	
Termination	Ag (or Cu)/Ni/Sn (lead-free termination)			

* Measured at the condition of 30~70% related humidity.

NPO: Apply 1.0±0.2Vrms, 1.0MHz±10% for Cap≤1000pF and 1.0±0.2Vrms, 1.0kHz±10% for Cap>1000pF, 25°C at ambient temperature

X7R: Apply 1.0±0.2Vrms, 1.0kHz±10%, at 25°C ambient temperature.

7.CAPACITANCE RANGE

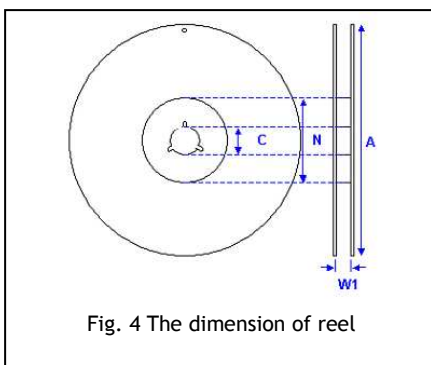
DIELECTRIC		NPO											
SIZE		1206		1210		1808			1812			0805	
RATED VOLTAGE		1000	2000	1000	2000	1000	2000	3000	1000	2000	3000	1000	
Capacitance	1.5pF (1R5)	B	B									D	
	1.8pF (1R8)	B	B									D	
	2.0pF (2R0)	B	B			D	D	D				D	
	2.2pF (2R2)	B	B			D	D	D				D	
	2.7pF (2R7)	B	B			D	D	D				D	
	3.3pF (3R3)	B	B			D	D	D				D	
	3.9pF (3R9)	B	B			D	D	D				D	
	4.7pF (4R7)	B	B			D	D	D				D	
	5.6pF (5R6)	B	B			D	D	D				D	
	6.8pF (6R8)	B	B			D	D	D				D	
	8.2pF (8R2)	B	B			D	D	D				D	
	10pF (100)	B	B	C	C	D	D	D	D	D	D	D	D
	12pF (120)	B	B	C	C	D	D	D	D	D	D	D	D
	15pF (150)	B	B	C	C	D	D	D	D	D	D	D	D
	18pF (180)	B	B	C	C	D	D	D	D	D	D	D	D
	22pF (220)	B	B	C	C	D	D	D	D	D	D	D	D
	27pF (270)	B	B	C	C	D	D	D	D	D	D	D	D
	33pF (330)	B	C	C	C	D	D	D	D	D	D	D	D
	39pF (390)	B	C	C	C	D	D	D	D	D	D	D	D
	47pF (470)	C	C	C	C	D	D	D	D	D	D	D	D
	56pF (560)	C	D	C	D	D	D	D	D	D	D	D	D
	68pF (680)	C	D	C	D	D	D	D	D	D	D	D	D
	82pF (820)	D	D	C	D	D	D	D	D	D	D	D	D
	100pF (101)	D	D	D	D	D	K	K	D	D	D	D	D
	120pF (121)	D	G	D	D	D	K	K	D	D	D	D	D
	150pF (151)	D	G	D	G	D	K	K	D	D	D	D	D
	180pF (181)	G	G	D	G	D	K	K	D	K	K	D	D
	220pF (221)	G	G	G	G	D	K	K	D	K	K	D	D
	270pF (271)	G	P	G	K	K	K	K	D	K	K	D	D
	330pF (331)	G	P	G	K	K	K	K	D	K	K	D	D
	390pF (391)	G	P	G	M	K	K		D	K	K	D	D
	470pF (471)	G		G	M	K	K		K	K	K		
	560pF (561)	G		G		K	K		K	K			
680pF (681)	G		G		K	K		K	K				
820pF (821)	G		G		K			K	K				
1,000pF (102)	G		G		K			K	K				
1,200pF (122)			G					K					
1,500pF (152)			K					K					
1,800pF (182)			M					K					
2,200pF (222)			M					K					
2,700pF (272)			M					K					
3,300pF (332)			M					K					
3,900pF (392)			M					M					

DIELECTRIC		X7R										
SIZE		1206		1210		1808			1812			0805
RATED VOLTAGE		1000	2000	1000	2000	1000	2000	3000	1000	2000	3000	1000
Capacitance	100pF (101)	D	D	D	D							B
	120pF (121)	D	D	D	D							B
	150pF (151)	D	D	D	D	D	D	D				B
	180pF (181)	D	D	D	D	D	D	D				B
	220pF (221)	D	D	D	D	D	D	D				B
	270pF (271)	D	D	D	D	D	D	D	D	D	K	B
	330pF (331)	D	D	D	D	D	D	K	D	D	K	B
	390pF (391)	D	D	D	D	D	D	K	D	D	K	B
	470pF (471)	D	D	D	D	D	D	K	D	D	K	B/D
	560pF (561)	D	D	D	D	D	D	K	D	D	K	B
	680pF (681)	D	D	D	D	D	D	K	D	D	K	B
	820pF (821)	D	D	D	D	D	D	K	D	D	K	B
	1,000pF (102)	D	B/C /D/G	D	D	D	K	K	D	D	K	B
	1,200pF (122)	D	G	D	M	D	K	K	D	D	K	B
	1,500pF (152)	D	G	D	M	D	K	K	D	D	K	D
	1,800pF (182)	D	G	D	M	D	K	K	D	D	M	D
	2,200pF (222)	D	C/G	D	M	D	K		D	D	M	D
	2,700pF (272)	D	G	D	M	D	K		D	D	M	D
	3,300pF (332)	D	G	D	M	D	K		D	K	M	D
	3,900pF (392)	D		G	M	D	K		D	K		D
	4,700pF (472)	D		G	M	D	K		D	K		D
	5,600pF (562)	D		G	M	K	K		D	M		D
	6,800pF (682)	D		G	M	K	K		D	M		D
	8,200pF (822)	D		G	M	K			D	M		D
	0.010μF (103)	D		G		K			D	M		
	0.012μF (123)	G		G		K			K			
	0.015μF (153)	G		G		K			K			
	0.018μF (183)			G		K			M			
	0.022μF (223)			G		K			M			
	0.033μF (333)			G		K			M			
0.039μF (393)			K		K			M				
0.047μF (473)			M		K			M				
0.056μF (563)			M		K			M				
0.068μF (683)			M					M				
0.10μF (104)								M				

8. PACKAGE DIMENSION AND QUANTITY

Size	Thickness (mm)	Paper tape		Plastic tape	
		7" reel	13" reel	7" reel	13" reel
1206 (3216)	0.85±0.15	4k	15k	-	-
	0.95±0.10	-	-	3k	10k
	1.25±0.20	-	-	3k	10k
	1.60±0.20	-	-	2k	-
1210 (3225)	0.95±0.10	-	-	3k	10k
	1.25±0.20	-	-	3k	10k
	1.60±0.20	-	-	2k	-
	2.00±0.20	-	-	1k	-
1808 (4520)	2.50±0.30	-	-	1k	-
	1.25±0.20	-	-	2k	-
	1.40±0.15	-	-	2k	-
	1.60±0.20	-	-	2k	-
1812 (4532)	2.00±0.20	-	-	1k	-
	1.25±0.20	-	-	1k	-
	1.60±0.20	-	-	1k	-
	2.00±0.20	-	-	1k	-
0805 (2012)	2.50±0.30	-	-	0.5k	3k
	0.85±0.15	4k	15k	-	-
	1.25±0.20	-	-	3k	10k

Unit: pieces



Size	0805 1206, 1210, 1812			1808, 1812, 1825, 2220, 2225
Reel size	7"	10"	13"	7"
C	13.0+0.5/-0.2	13.0+0.5/-0.2	13.0+0.5/-0.2	13.0+0.5/-0.2
W ₁	8.4+1.5/-0	8.4+1.5/-0	8.4+1.5/-0	12.4+2.0/-0
A	178.0±0.10	250.0±1.0	330.0±1.0	178.0±0.10
N	60.5±1.0	100.0±1.0	100±1.0	60.5±1.0

8-1. CARDBOARD TAPE DIMENSIONS

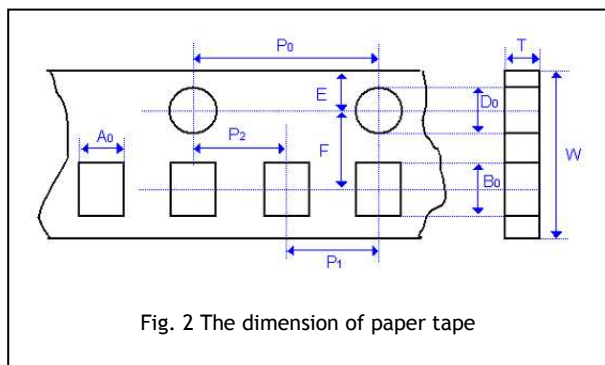


Fig. 2 The dimension of paper tape

8-2. EMBOSED TAPE DIMENSIONS

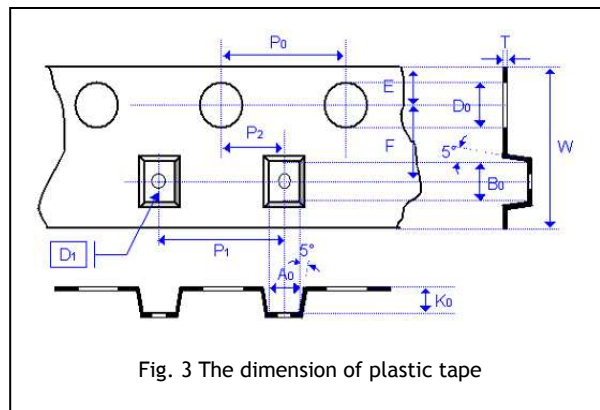


Fig. 3 The dimension of plastic tape

Size	0805		1206			1210		1808	
Chip Thickness	0.80±0.10	1.25±0.10	0.80±0.10	0.95±0.10 1.25±0.10	1.60±0.20 1.60+0.3/-0.1	0.95±0.10 1.25±0.10 1.60±0.20 2.00±0.20	2.50±0.30	1.25±0.10 1.40±0.15 1.60±0.20	2.00±0.20
A ₀	1.5±0.20	<1.80	2.00±0.10	<2.00	<2.00	<3.05	<3.10	<2.50	<2.50
B ₀	2.3±0.20	<2.70	3.50±0.10	<3.60	<3.70	<3.80	<4.00	<5.30	<5.30
T	≤ 1.20	0.23±0.10	0.95±0.05	0.23±0.05	0.23±0.05	0.23±0.05	0.23±0.05	0.25±0.05	0.25±0.05
K ₀			-	<2.50	<2.50	<2.50	<3.50	<2.50	<2.50
W	8.0±0.30	8.0±0.30	8.00±0.10	8.00±0.10	8.00±0.10	8.00±0.10	8.00±0.10	12.0±0.20	12.0±0.20
P ₀	4.0±0.10	4.0±0.10	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.100	4.00±0.10	4.00±0.10	4.00±0.10
10xP ₀	40±0.20	40±0.20	40.0±0.20	40.00±0.20	40.00±0.20	40.00±0.20	40.0±0.20	40.0±0.20	40.0±0.20
P ₁	4.0±0.10	4.0±0.10	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10
P ₂	2.0±0.05	2.0±0.05	2.00±0.05	2.00±0.05	2.00±0.05	2.00±0.05	2.00±0.05	2.00±0.05	2.00±0.05
D ₀	1.5+0.1/-0	1.5+0.1/-0	1.50±0.05	1.50±0.10/-0	1.50±0.10/-0	1.50±0.10/-0	1.50±0.10/-0	1.50±0.10/-0	1.50±0.10/-0
D ₁		1.0±0.10	-	1.00±0.10	1.00±0.10	1.00±0.10	1.00±0.10	1.50±0.10	1.50±0.10
E	1.75±0.10	1.75±0.10	1.75±0.10	1.75±0.10	1.75±0.10	1.75±0.10	1.75±0.10	1.75±0.10	1.75±0.10
F	3.5±0.05	3.5±0.05	3.50±0.05	3.50±0.05	3.50±0.05	3.50±0.05	3.50±0.05	5.50±0.05	5.50±0.05

9. APPLICATION NOTES

STORAGE

To prevent the damage of solderability of terminations, the following storage conditions are recommended:

Indoors under 5 ~ 40°C and 20% ~ 70% RH.

No harmful gases containing sulfuric acid, ammonia, hydrogen sulfide or chlorine.

Packaging should not be opened until the capacitors are required for use. If opened, the pack should be re-sealed as soon as is practicable. Taped product should be stored out of direct sunlight, which might promote deterioration in tape or adhesion performance. The capacitors should be used within 6 months and checked the solderability before use.

HANDLING

Chip capacitors are dense, hard, brittle, and abrasive materials. They are liable to suffer mechanical damage, in the form of cracks or chips. Chip Capacitors should be handled with care to avoid contamination or damage. To use vacuum or plastic tweezers to pick up or plastic tweezers is recommended for manual placement. Tape and reeled packages are suitable for automatic pick and placement machine.

PREHEAT

In order to minimize the risk of thermal shock during soldering, a carefully controlled preheat is required. The rate of preheat should not exceed 4°C per second and the final preheat temperature should be within 100°C of the soldering temperature for small chips such as 1206, within 50°C of the soldering temperature for bigger chips such as 1210, 1808, 1812, 1825, 2220 and 2225, etc.

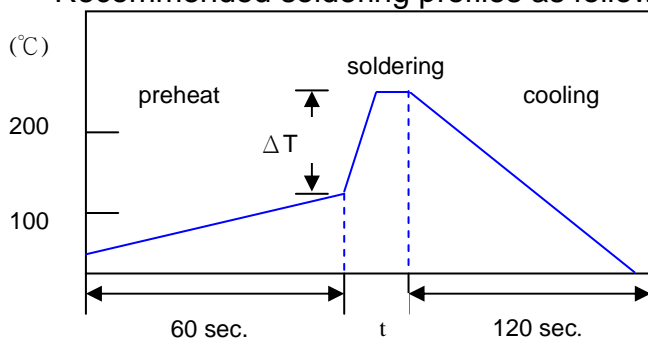
SOLDERING

Use middy activated rosin RA and RMA fluxes do not use activated flux. The amount of solder in each solder joint should be controlled to prevent the damage of chip capacitors caused by the stress between solder, chips, and substrate.

Hand soldering with temperature-controlled iron not exceeding 30 watts and diameter of tip less than 1.2 mm is recommended, tip of iron should not contact the ceramic body directly, and the temperature of iron should be set to not more than 260°C.

For bigger chips such as 1210, 1808, 1812, 2220 and 2225, etc. wave soldering and hand soldering are no recommended.

Recommended soldering profiles as following:



Soldering	Solder Temp.(T)	Soldering Time (t)
Reflow	235 – 260 °C	< 15 sec.
Wave	230 – 260 °C	< 5 sec.

Chip Size	ΔT
1206	100 °C
1210, 1808, 1812, 1825, 2220, 2225	50 °C

COOLING

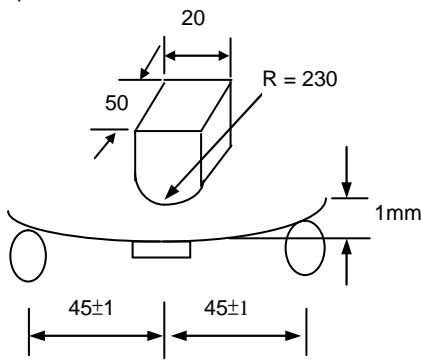
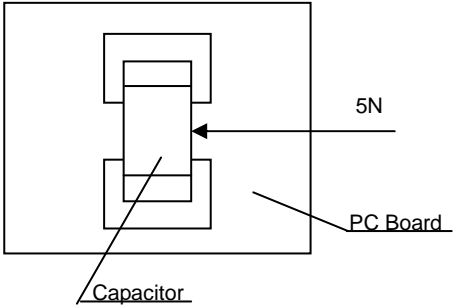
After soldering, cool the chips and the substrate gradually to room temperature. Natural cooling in air is recommended to minimize stress in the solder joint. A cooling rate not exceeding 4°C per second should be used when forced cooling is necessary.

CLEANING

All flux residues must be removed by using suitable electronic-grade vapor-cleaning solvents to eliminate contamination that could cause electrolytic surface corrosion. Good results can be obtained by using ultrasonic cleaning of the solvent. The choice of the proper system is depends upon many factors such as component mix, flux, and solder paste and assembly method. The ability of the cleaning system to remove flux residues and contamination from under the chips is very important.

10.RELIABILITY TEST CONDITIONS AND REQUIREMENTS

No.	Item	Test Condition	Requirements															
1.	Visual and Mechanical	---	* No remarkable defect. * Dimensions to conform to individual specification sheet.															
2.	Capacitance	Class I: (NP0)	* Shall not exceed the limits given in the detailed spec.															
3.	Q/ D.F. (Dissipation Factor)	Cap \leq 1000pF, 1.0 \pm 0.2Vrms, 1MHz \pm 10% Cap $>$ 1000pF, 1.0 \pm 0.2Vrms, 1KHz \pm 10% Class II: (X7R) 1.0 \pm 0.2Vrms, 1kHz \pm 10%	NP0: Cap \geq 30pF, Q \geq 1000; Cap $<$ 30pF, Q \geq 400+20C X7R: \leq 2.5%															
4.	Temperature Coefficient	With no electrical load. <table border="1"> <thead> <tr> <th>T.C.</th> <th>Operating Temp</th> </tr> </thead> <tbody> <tr> <td>NP0</td> <td>-55~125°C at 25°C</td> </tr> <tr> <td>X7R</td> <td>-55~125°C at 25°C</td> </tr> </tbody> </table>	T.C.	Operating Temp	NP0	-55~125°C at 25°C	X7R	-55~125°C at 25°C	<table border="1"> <thead> <tr> <th>T.C.</th> <th>Capacitance Change</th> </tr> </thead> <tbody> <tr> <td>NP0</td> <td>Within \pm30ppm/°C</td> </tr> <tr> <td>X7R</td> <td>Within \pm15%</td> </tr> </tbody> </table>	T.C.	Capacitance Change	NP0	Within \pm 30ppm/°C	X7R	Within \pm 15%			
T.C.	Operating Temp																	
NP0	-55~125°C at 25°C																	
X7R	-55~125°C at 25°C																	
T.C.	Capacitance Change																	
NP0	Within \pm 30ppm/°C																	
X7R	Within \pm 15%																	
5.	Insulation Resistance	* To apply voltage at 500VDC for 60 sec.	Class I (NP0) : \geq 100G Ω or Rx $C \geq$ 1000 Ω -F whichever is smaller. Class II (X7R) : \geq 10G Ω or Rx $C \geq$ 500 Ω -F whichever is smaller.															
6.	Dielectric Strength	* To apply voltage: 1.2 times of U _R * Duration: 1 to 5 sec.	* No evidence of damage or flashover during test.															
7.	Solderability	* Solder temperature: 235 \pm 5°C * Dipping time: 5 \pm 0.5 sec.	75% min. coverage of all metalized area.															
8.	Resistance to Soldering Heat	* Solder temperature: 260 \pm 5°C * Dipping time: 10 \pm 1 sec * Preheating: 120 to 150°C for 1 minute before immerse the capacitor in a eutectic solder. * Before initial measurement (Class II only): Perform 150+0/-10°C for 1 hr and then set for 48 \pm 4 hrs at room temp. * Measurement to be made after keeping at room temp. for 24 \pm 2hrs (Class I) or 48 \pm 4 hrs (Class II).	* No remarkable damage. * Cap change: NP0: within \pm 2.5% or \pm 0.25pF whichever is larger. X7R: within \pm 7.5% * 25% max. leaching on each edge.															
9.	Temperature Cycle	* Conduct the five cycles according to the temperatures and time. <table border="1"> <thead> <tr> <th>Step</th> <th>Temp. (°C)</th> <th>Time (min.)</th> </tr> </thead> <tbody> <tr> <td>1</td> <td>Min. operating temp. +0/-3</td> <td>30\pm3</td> </tr> <tr> <td>2</td> <td>Room temp.</td> <td>2~3</td> </tr> <tr> <td>3</td> <td>Max. operating temp. +3/-0</td> <td>30\pm3</td> </tr> <tr> <td>4</td> <td>Room temp.</td> <td>2~3</td> </tr> </tbody> </table> * Before initial measurement (Class II only): Perform 150+0/-10°C for 1 hr and then set for 48 \pm 4 hrs at room temp. * Measurement to be made after keeping at room temp. for 24 \pm 2 hrs (Class I) or 48 \pm 4 hrs (Class II).	Step	Temp. (°C)	Time (min.)	1	Min. operating temp. +0/-3	30 \pm 3	2	Room temp.	2~3	3	Max. operating temp. +3/-0	30 \pm 3	4	Room temp.	2~3	* No remarkable damage. * Cap change : NP0: within \pm 2.5% or \pm 0.25pF whichever is larger. X7R: within \pm 15% * Q/D.F.: NP0: \leq 2.0 \times Initial requirement X7R: \leq 1.5 \times Initial requirement * I.R. \geq 0.25 \times initial requirement
Step	Temp. (°C)	Time (min.)																
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3	Max. operating temp. +3/-0	30 \pm 3																
4	Room temp.	2~3																
10.	Humidity (Damp Heat) Steady State	* Test temp.: 40 \pm 2°C * Humidity: 90~95% RH * Test time: 500+24/-0hrs. * Measurement to be made after keeping at room temp. for 24 \pm 2 hrs (Class I) or 48 \pm 4 hrs (Class II).	* No remarkable damage. * Cap change: NP0 within \pm 5% or \pm 2pF whichever is larger X7R within \pm 15% * Q/D.F Value: NP0: Cap \geq 30pF :Q \geq 350 10pF \leq Cap $<$ 30pF :Q \geq 275+2.5C Cap $<$ 10pF :Q \geq 200+10C X7R: \leq 7.0% * I.R.: \geq 1G Ω or Rx $C \geq$ 50 Ω -F whichever is smaller.															
11.	High Temperature Load (Endurance)	* Test temp.: NP0, X7R: 125 \pm 3°C * To apply voltage: 120% of rated voltage. * Test time: 1000+24/-0 hrs. * Measurement to be made after keeping at room temp. for 24 \pm 2 hrs (Class I) or 48 \pm 4 hrs (Class II).	* No remarkable damage. * Cap change: NP0: within \pm 3% or \pm 3pF whichever is larger. X7R: within \pm 20% * Q/D.F value: NP0: Cap \geq 30pF :Q \geq 350 10pF \leq Cap $<$ 30pF :Q \geq 275+2.5C Cap $<$ 10pF :Q \geq 200+10C X7R: \leq 7.0% * I.R.: \geq 10V, \geq 1G Ω or Rx $C \geq$ 50 Ω -F whichever is smaller.															

No.	Item	Test Condition	Requirements
12.	Resistance to Flexure of Substrate	<p>* The middle part of substrate shall be pressurized by means of the pressurizing rod at a rate of about 1 mm per second until the deflection becomes 1 mm.</p> 	<p>* No remarkable damage. * Cap change : NP0 : within $\pm 10\%$ X7R : within $\pm 12.5\%$</p> <p>(This capacitance change means the change of capacitance under specified flexure of substrate from the capacitance measured before the test.)</p>
13.	Adhesive Strength of Termination	<p>* Capacitors mounted on a substrate. A force of 5N applied perpendicular to the place of substrate and parallel the line joining the center of terminations for 10 ± 1 sec.</p> 	<p>* No remarkable damage or removal of the terminations.</p>